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# larking Conventions

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#### Overview

National Semiconductor marks devices sold in order to provide device identification and manufacturing traceability informat method of presenting the information marked on the device is dependent on the size of the device package and the area at marking as well as the nature and specifications of the device.

The information presented here describes the majority of the device marking a customer will observe. Specific package may on a device by device basis in our Price & Availability section of this web site.

The links below discuss general marking conventions to help understand device markings similar to those in the examples

**Special Codes** 

Standard First Line Manufacturing Information

Small Component First Line Manufacturing Info

Typical Device Descriptions (Second Line)

Optional Third and Fourth Line Information

Very Small Component Marking

Mil/Aero Marking

**Enhanced Plastic** 

Additional Markings

Wafer Fab Plant Codes

**Assembly Plant Codes** 

**Date of Manufacture Codes** 

Die Run Codes

Device Families, Product Lines and Device Type



**Electrical Grade Information** AND PACKAGING Temperature Range Code rking Conventions **Packaging Codes** ditional Information **ROM Code Markings** ad-Free Packaging **NFORMATION** Special Codes commendationsHandling & cess (pdf) Actual Top Mark content may vary from the web definition. The Special Codes below are decoded to the actual characters marking. National may use specific characters to better identify it's products, for example "DD" Die Step Rev, this may conor "AA" reference in the part marking. Another example, "BBBBB" is a 5 digit Die Revision Number may be decoded as "43 NT PROFILES actual characters. iability Test Services NS = Standard NS Logo HITE PAPERS U = Wafer Fab Code ects in DMOS Z = Assembly Plant Code enna Ratio Violation X = 1-Datecode or + PLUS SIGN For "ES" Engineering Samples L INFORMATION XY = 2-Digit Datecode XYY = 3-Digit Datecode S/ESD InformationObsolete XXYY = 4-Digit Datecode duct Listings TT = 2-Digit D/Run vironmental Safety E# = Lead Finish Category \* (E0 - E7 per JESD97) ssary: Quality Terms BBBBB = Five Digit Dierun Code JS DD = 1 or 2 Digit Diestep Rev mments & Questions SS = Wafer Sort Code tional Locations = Copyright Symbol C Within a Circle = M Inscribed Within A Circle = ESD Symbol

EP = Enhanced Plastic Identification

A = Inspection Lot Number

DIE-RUN-## = 10 Digit Wafer Lot/Die Run Number

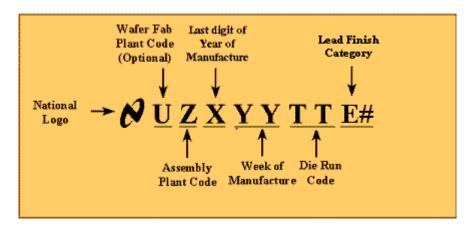
I = Micro SMD Pin 1 Designator

V = Micro SMD 1-Digit D/Run or + plus sign for "ES" Engineering Sample

\* - If space permits

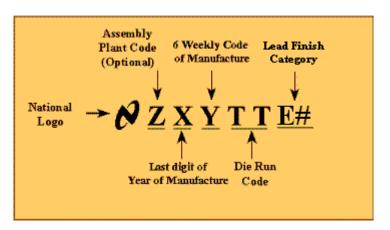
### Standard First Line Manufacturing Information

The first line of device marking provides manufacturing information as shown in the schematic below.



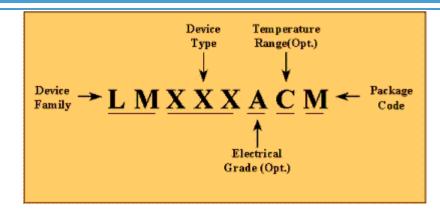
### Small Component First Line Manufacturing Information

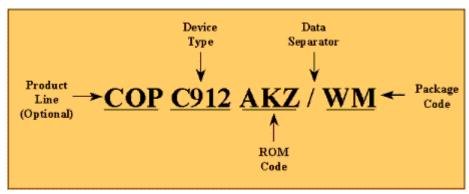
On smaller packages, such as SOICs, 8-lead MDIPs, and 20-lead PLCCs, the information is encoded somewhat differently accommodate the smaller area available as shown in the schematic below.



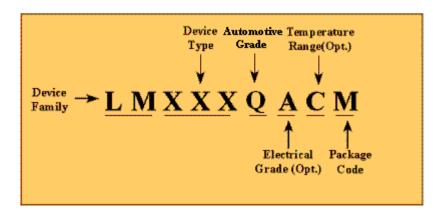
# **Typical Device Descriptions (Second Line)**

The second line of marking describes the specific circuit in the package. The schematics below show information shown fo well as programmable devices.





Automotive Grade products will have a unique NSID. The letter "Q" will be added to the standard commercial product mark NSID.See schematics below.



### **Optional Third and Fourth Line Information**

Depending on the device, package size, and customer, additional information might appear in a third or fourth line of markinformation that might appear on these lines include:

Continuation of device identification (if too long for the second line)

"Stampoff" number as required by specific customer request and specification

Notice(s) related to copyright (©) or trademarks (™, ®)

## **Very Small Component Marking**

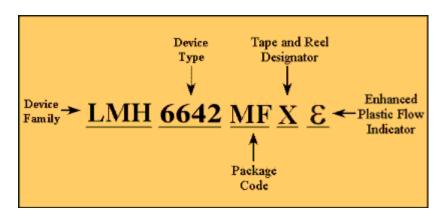
Certain very small packages, such as SOT-23, SOT-223, SC70, and SC90, are too small to contain all the information disc Device identification marking is assigned differently and can be found in the **Availability, Models, Samples & Pricing** sec device's Part Number link from the **Master Selection Guide**. Other date code information, which would be typically found in marking, is identified on the container labels.

### Mil/Aero Marking

Top marking information for National's Mil/Aero Products. Mil/Aero Marking Guide (pdf 63KB).

#### **Enhanced Plastic**

National's Enhanced Plastic (EP) Products are for system requirements which dictate an upgrade from standard commerci product (COTS), but don't need the additional requirements associated with QML systems. EP products give customers the facilitate their internal qualification of COTS devices, by making available: extended temperature ranges, qualification data and baseline control, and more.



### **Additional Marking**

With the wide range of product produced by National Semiconductor, additional marking is sometimes needed to indicate a of performance or to identify specific functionality. For example, some marks that might occur after the package code or disinclude the following:

Special reliability processing (/A+)

Processing to MIL-STD-883C (/883)

Indication of adjustable output device (-ADJ)

Indication of output voltage level (-5.0)

Indication of operation frequency (-33)

Marketing status code (ES)

Other information as discussed above

As always, the best source for final confirmation of marking interpretation is to review the information available in the Maste Guide.

### Wafer Fab Plant Codes

The following table list single letter codes for National Semiconductor's wafer fabrication plants. Letters that don't appear of indicate wafer fabrication at one of National Semiconductor's approved sub-contractors.

Code	Fab Location
Е	Arlington, TX
Н	Greenock, UK
J	Greenock, UK
V	South Portland, ME
Х	Arlington, TX

Code	Foundries
2	Taiwan
4	Taiwan
6	Taiwan
7	Taiwan
9	Taiwan
D	Italy
G	Taiwan
I	France
K	Taiwan
М	USA
N	Israel
Р	China
Q	China
R	Taiwan
S	China
U	Taiwan
W	USA

## **Assembly Plant Codes**

The following table list single letter codes for National Semiconductor's device assembly plants. Letters that don't appear o indicate device assembly at another of National Semiconductor's approved sub-contractors.

Code	Assembly Location
F	Santa Clara, CA
М	Malacca, Malaysia
S	Singapore

Code	Assembly Location
А	Philippines (Sub-con)
K	Hong Kong (Sub-con)
N	Malaysia (Sub-con)

С	China
L	Taiwan (Sub-con)
R	Malaysia (Sub-con)
0	Taiwan (Sub-con)
Q	China (Sub-con)
G	China (Sub-con)
U	China (Sub-con)
В	Thailand (Sub-con)
V	Malaysia (Sub-con)

J	Japan (Sub-con)
Е	Korea (Sub-con)
Р	Malaysia (Sub-con)
Н	Philippines (Sub-con)
Т	Taiwan (Sub-con)
Υ	Malaysia (Sub-con)
Х	USA (Sub-con)
I	Taiwan (Sub-con)
Z	U.S.A (Sub-con)

### **Date of Manufacture Codes**

### **Unit Date Code:**

The unit date code markings are in 4 digits, 3 digits, 2 digits or single digit formats. The 4 digit date code is used mainly for devices. The 3 digit date codes is used for standard commercial devices where the package marking surface is large enouthe required marking information. The 2 digit and the single digit date codes are used on small packages where the markin limited.

### Commercial parts:

The custom commercial parts have weekly date code where the date code changes weekly according to the calendar wee commercial parts plus all small packages have 6 weekly date codes where the date code changes every 6 weeks. Even th codes change every 6 weeks, using the NSID, the date code and the dierun code, the exact date of production start can be National's on-line traceability system.

The 6-weekly date codes are as below.

2015	2014	2013	2012
XXYY XYY XY X			
1506 506 51 J	1406 406 41 A	1306 306 31 S	1206 206 21 J
1512 512 52 K	1412 412 42 B	1312 312 32 T	1212 212 22 K
1518 518 53 L	1418 418 43 C	1318 318 33 U	1218 218 23 L
1524 524 54 M	1424 424 44 D	1324 324 34 V	1224 224 24 M
1530 530 55 N	1430 430 45 E	1330 330 35 W	1230 230 25 N
1536 536 56 6	1436 436 46 F	1336 336 36 X	1236 236 26 6
1542 542 57 P	1442 442 47 G	1342 342 37 Y	1242 242 27 P
1548 548 58 8	1448 448 48 H	1348 348 38 Z	1248 248 28 8
1552 552 59 R	1452 452 49 9	1352 352 39 =	1252 252 29 R

2011	2010	2009	2008
XXYY XYY XY X			
1106 106 11 A	1006 006 01 S	0906 906 91 J	0806 806 81 A
1112 112 12 B	1012 012 02 T	0912 912 92 K	0812 812 82 B
1118 118 13 C	1018 018 03 U	0918 918 93 L	0818 818 83 C
1124 124 14 D	1024 024 04 V	0924 924 94 M	0824 824 84 D
1130 130 15 E	1030 030 05 W	0930 930 95 N	0830 830 85 E
1136 136 16 F	1036 036 06 X	0936 936 96 6	0836 836 86 F
1142 142 17 G	1042 042 07 Y	0942 942 97 P	0842 842 87 G
1148 148 18 H	1048 048 08 Z	0948 948 98 8	0848 848 88 H
1152 152 19 9	1052 052 09 =	0952 952 99 R	0852 852 89 9
2007	2006	2005	2004
XXYY XYY XY X			
0706 706 71 S	0606 606 61 J	0506 506 51 A	0406 406 41 S
0712 712 72 T	0612 612 62 K	0512 512 52 B	0412 412 42 T
0718 718 73 U	0618 618 63 L	0518 518 53 C	0418 418 43 U
0724 724 74 V	0624 624 64 M	0524 524 54 D	0424 424 44 V
0730 730 75 W	0630 630 65 N	0530 530 55 E	0430 430 45 W
0736 736 76 X	0636 636 66 6	0536 536 56 F	0436 436 46 X
0742 742 77 Y	0642 642 67 P	0542 542 57 G	0442 442 47 Y
0748 748 78 Z	0648 648 68 8	0548 548 58 H	0448 448 48 Z
0752 752 79 =	0652 652 69 R	0552 552 59 9	0452 452 49 =
2003	2002	2001	2000
XXYY XYY XY X			
0306 306 31 J	0206 206 21 A	0106 106 11 S	0006 006 01 J
0312 312 32 K	0212 212 22 B	0112 112 12 T	0012 012 02 K
0318 318 33 L	0218 218 23 C	0118 118 13 U	0018 018 03 L
0324 324 34 M	0224 224 24 D	0124 124 14 V	0024 024 04 M

0330 330 35 N	0230 230 25 E	0130 130 15 W	0030 030 05 N
0336 336 36 O	0236 236 26 F	0136 136 16 X	0036 036 06 O
0342 342 37 P	0242 242 27 G	0142 142 17 Y	0042 042 07 P
0348 348 38 Q	0248 248 28 H	0148 148 18 Z	0048 048 08 Q
0352 352 39 R	0252 252 29 I	0152 152 19 =	0052 052 09 R
1999	1998	1997	1996
XXYY XYY XY X			
9906 906 91 A	9806 806 81 S	9706 706 71 J	9606 606 61 A
9912 912 92 B	9812 812 82 T	9712 712 72 K	9612 612 62 B
9918 918 93 C	9818 818 83 U	9718 718 73 L	9618 618 63 C
9924 924 94 D	9824 824 84 V	9724 724 74 M	9624 624 64 D
9930 930 95 E	9830 830 85 W	9730 730 75 N	9630 630 65 E
9936 936 96 F	9836 836 86 X	9736 736 76 O	9636 636 66 F
9942 942 97 G	9842 842 87 Y	9742 742 77 P	9642 642 67 G
9948 948 98 H	9848 848 88 Z	9748 748 78 Q	9648 648 68 H
9952 952 99 I	9852 852 89 =	9752 752 79 R	9652 652 69 I

#### **Die Run Codes**

The die run code is a two letter alpha code that is automatically assigned to each lot by an internal manufacturing system. problems with a device, this code facilitates backward traceability to manufacturing processes where containment and corr can be defined. These actions, in turn, minimize, and eventually eliminate, any negative impact on customers.

### **Device Families, Product Lines and Device Types**

Basic device identification is usually provided in the second line of device marking. As indicated, the general form of the identification in the specific device. The table below lists a sampling of device family prefixes, can be found in the Master Selection Guide.

Code	Product Family
ADC	Data Conversion
CGS	Clock Generation Support
COP	Control Oriented Processor
DAC	Data Conversion
DP	Local Area Network Products

Code	Product Family
DS	Interface Products
LM	Linear
LMX	Frequency Synthesizers / PLL
LP	Voltage Regulators
PC	PC Related Products

#### **Electrical Grade Information**

When present, additional markings between the device identification characters and the package code represent device vabe thought of as "grade levels" of the product. These might represent:

Improved precision

An improved die revision

Wider or more narrow specification range

Accuracy vs temperature levels

The exact nature of the variations are defined in product datasheets which can be viewed via links in the Master Selection

#### **Temperature Range Codes**

The temperature range over which a device's operation is specified may vary over different versions of the basic device. In temperature range code indicates the specified range. While the list below lists the most common ranges specified, custom confirm this data on the datasheets accessible from the product links in the Master Selection Guide.

0°C to +70°C (Code C)

-40°C to +85°C (Code I)

-55°C to +125°C (No code)

### **Packaging Codes**

To meet customer needs, National Semiconductor offers its products in a wide variety of packaging options. The package for each device type can be viewed in the Master Selection Guide. From the selection guide, links are available to obtain d information on each package type such as mechanical and thermal specifications.

A small sample of packaging codes found within the device description marking is given in the table below:

Code	Package
Н	TO-5 / TO-46
J	CERDIP
М	SOP / SOIC
MX	SOP Tape & Reel
N	Molded DIP

Code	Package
S	TO-263
Т	TO-220
U	Pin Grid Array
V	Plastic Chip Carrier (PCC)
VF	Quad Flat Pak (PQFP)

### **ROM Marking Codes**

Products such as Single-Chip Microcontrollers use the same basic device with different on-board programming to achieve

functionality. ROM code marking identifies a specific device according to the internal programming.